

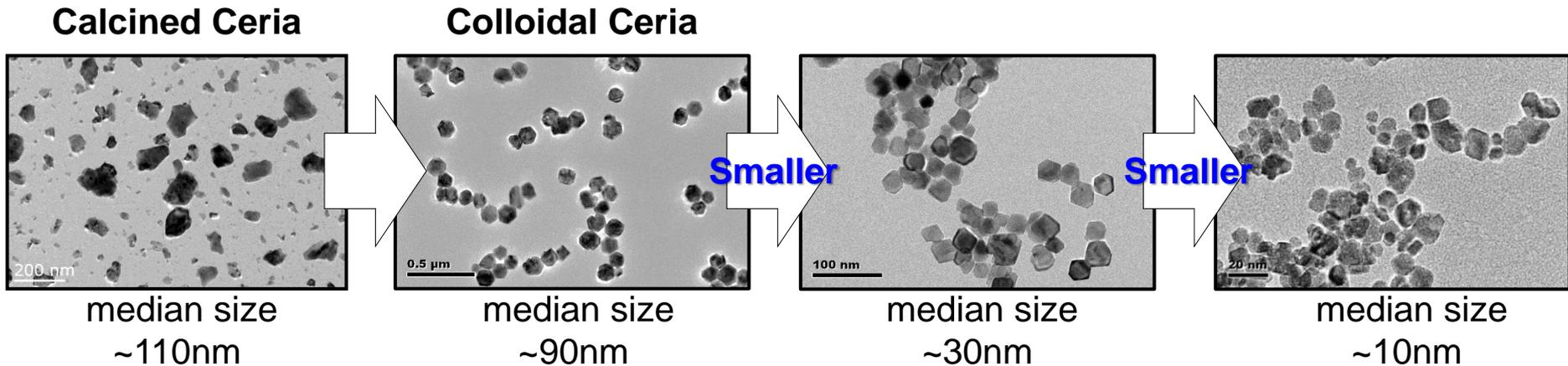
Almost Complete Removal of Sub-90 nm Ceria Particles from Silicon Dioxide Surfaces

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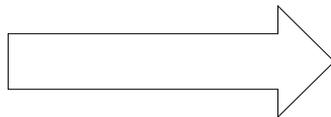
The Center for Advanced Materials Processing (CAMP),
Clarkson University

1. Introduction
2. Physico-chemical Properties of Ceria Particles with different sizes
: Contamination and Cleaning
3. H_2O_2 - NH_4OH Mixtures and Their Optimization
4. Investigation of Mechanism of the Cleaning of Ceria Particles
using H_2O_2 -based Alkaline Solutions from Silicon Dioxide Surfaces
5. Summary

Trends of Ceria Slurries



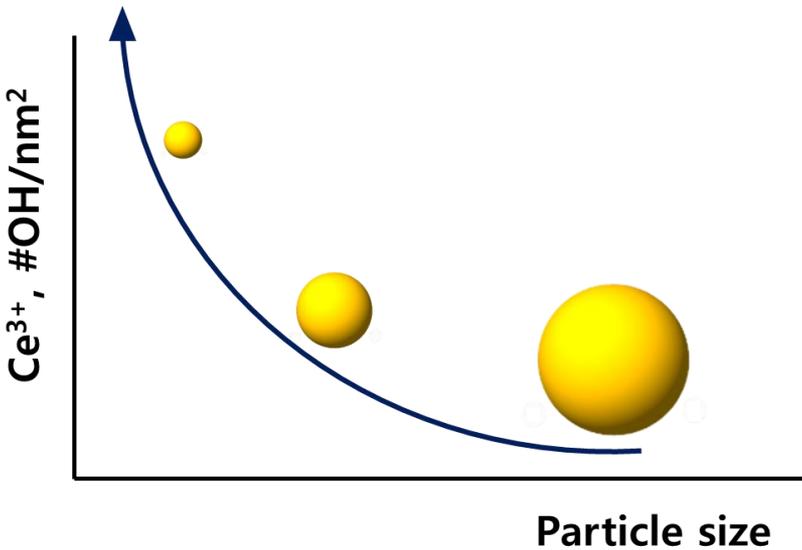
- High SiO₂ removal rate
- High crystallinity
- Tunable particle size
- Mass production
- Facet shape
- Poor size distribution
- Relatively high scratch



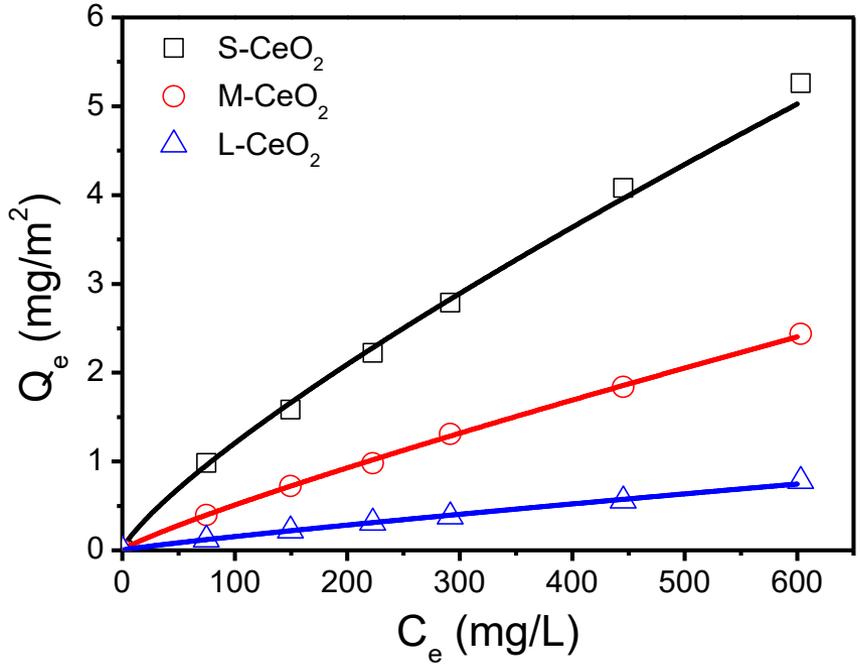
- Uniform size distribution
- Spherical shape
- Low scratch
- High cost
- Relatively Low SiO₂ RR

Interaction between Ceria particle and SiO₂ surface

Size-dependent surface chemistry of ceria



Adsorption of silicate ion on ceria surface



	Adsorption constant		
	K _F	1/n	R ²
S-CeO ₂	0.0570	0.6771	0.9646
M-CeO ₂	0.0207	0.7135	0.9639
L-CeO ₂	0.0048	0.7650	0.9797

Traditional Cleaning Solutions

1 Piranha (98% H_2SO_4 : 30% H_2O_2 - 4 : 1) at 90 ~ 120 °C

-Removal of organic contaminants

2 SC-1 (29% NH_4OH : 30% H_2O_2 : H_2O - 1 : 1 : 5) at 80 ~ 90°C

-Removal of particles and organic contaminants

3 SC-2 (37% HCl : 30% H_2O_2 : H_2O - 1 : 1 : 5) at 80 ~ 90 °C

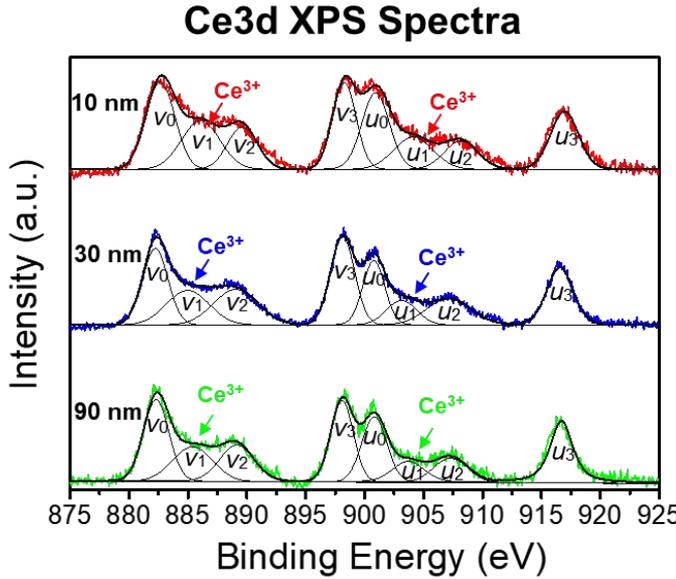
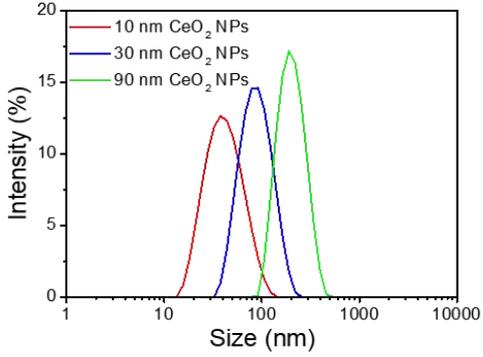
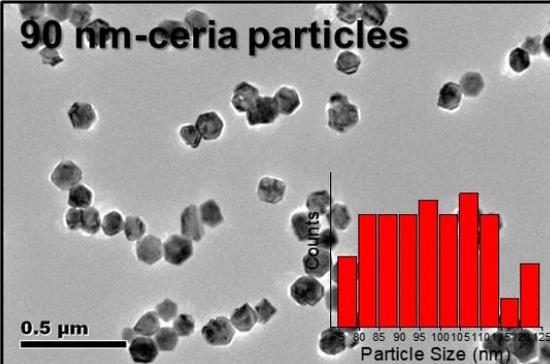
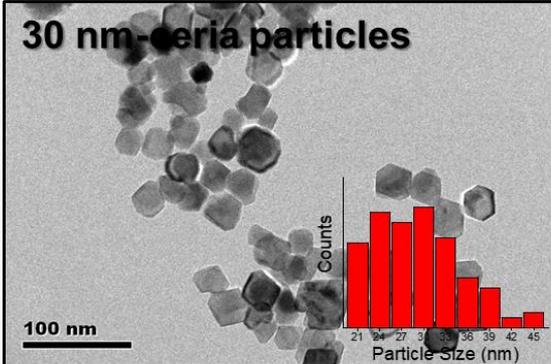
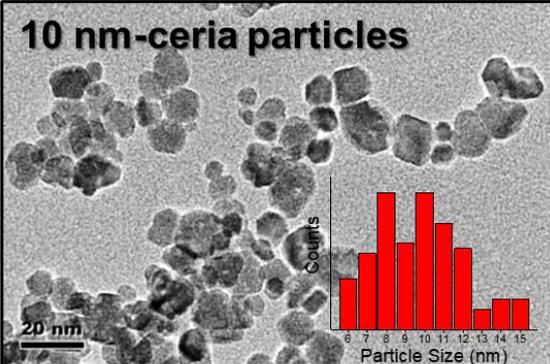
-Removal of metallic contaminants

4 DHF (dilute HF, typically less than 0.5 vol% of 47% HF) at 25 °C

-Removal of a thin oxide layer

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Physico-chemical properties of ceria particles with different sizes



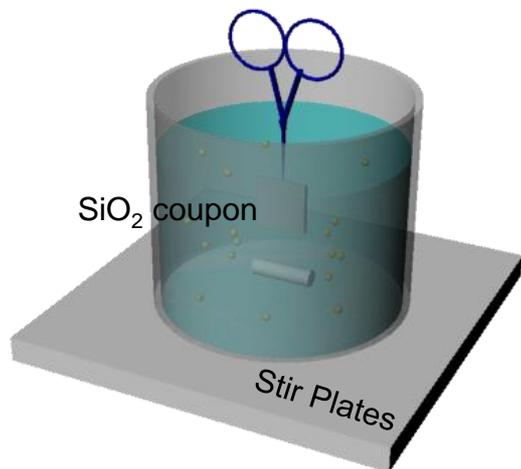
	S_{BET} (m^2/g)	d_{BET}^a (nm)	d_{TEM}^b (nm)	d_{DLS}^c (nm)	Ce^{3+} (%)
10 nm-ceria	84.3	10 nm	10 nm	36 nm	26.3 %
30 nm-ceria	28.8	29 nm	29 nm	81 nm	18.4 %
90 nm-ceria	8.0	98 nm	104 nm	193 nm	15.0 %

Table. Physicochemical properties of ceria particles with different sizes.

^aObtained from Solvay. ^bCalculated from TEM image. ^cMeasured using DLS method

Our lab-based evaluation method for cleaning study

1st) Preparation of contaminated coupon



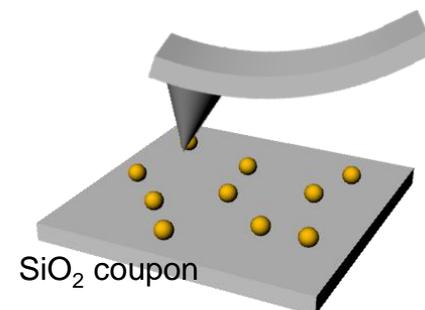
Slurry

- CeO₂ 0.05 wt%
- Volume: 100 mL

Conditions

- Sample size: 1 x 1 cm²
- Time: 60s @ 300 rpm
- Temperature : 25 °C

DIW rinsing

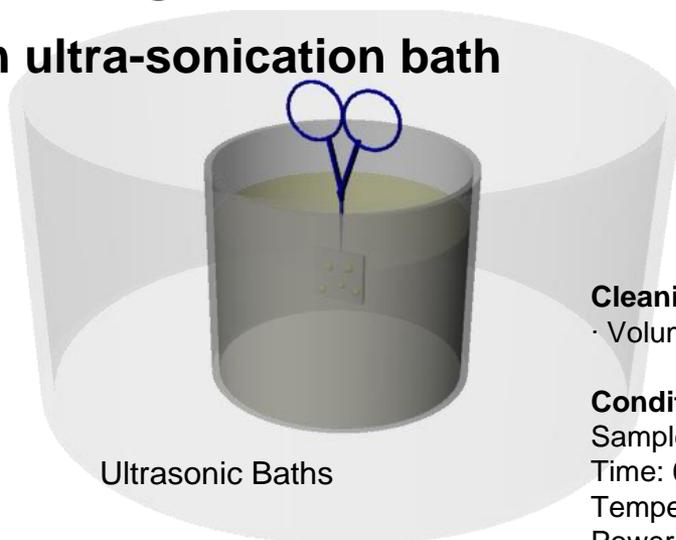


AFM measurements

- Park Systems (XE-300P)
- Non-Contact with NCHR
- Scan rate 0.5 Hz

2nd) Cleaning with our solutions

in ultra-sonication bath



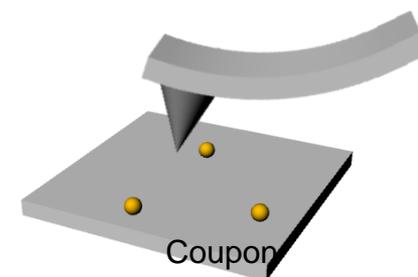
Cleaning solutions

- Volume: 100 mL

Conditions

- Sample size: 1 x 1 cm²
- Time: 60s
- Temperature : 25 °C
- Power : 75 W, Frequency: ~40 kHz

DIW rinsing



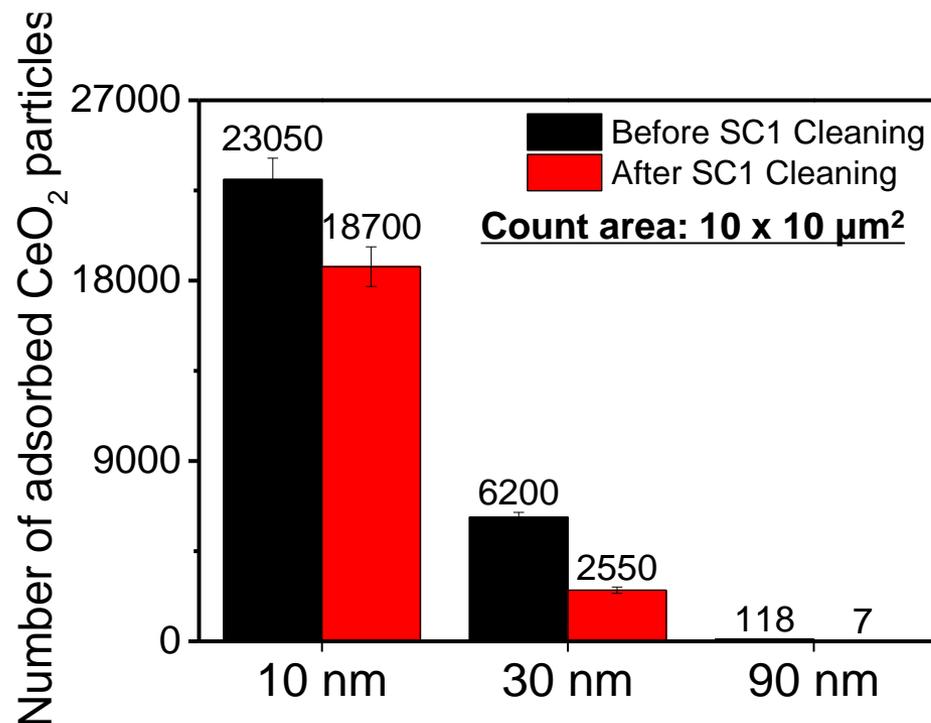
Cleaning efficiencies (CE)

$$= \frac{\text{Particle (initial)} - \text{Particle (residual)}}{\text{Particle (initial)}}$$

Size-dependent Cleaning Efficiency

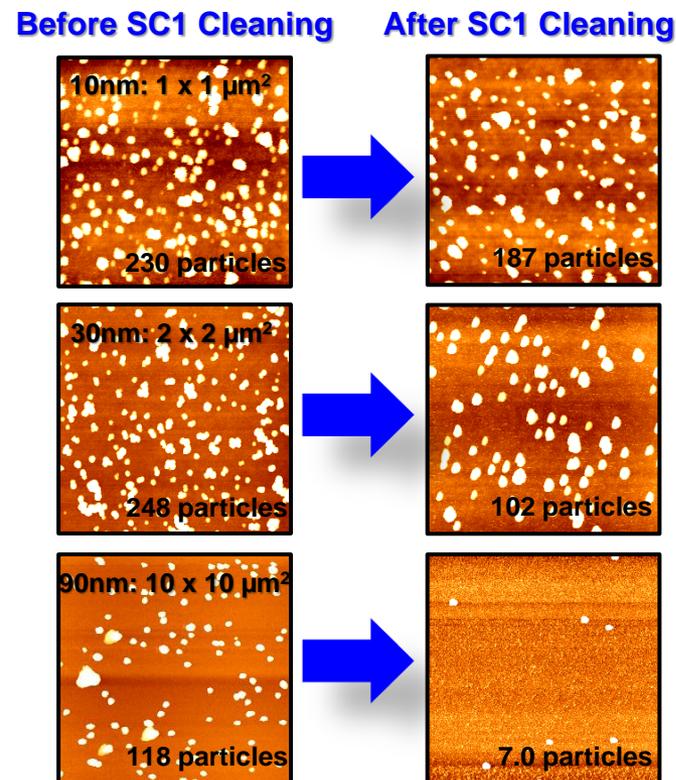
SC1 solution consisting of 1:1:5 (v/v/v) mixture of NH_4OH (30 wt%)/ H_2O_2 (30 wt%)/DIW

Number of ceria particles before and after SC1 Cleaning



	10 nm	30 nm	90 nm
Cleaning Efficiency	19 %	58 %	94 %

$$\text{Cleaning Efficiency (CE)} = \frac{\text{CeO}_2 (\text{initial}) - \text{CeO}_2 (\text{residual})}{\text{CeO}_2 (\text{initial})} \times 100$$



Number of ceria particles in scan area

H₂O₂-NH₄OH mixtures and Their Optimization

Design of experiments (DOE)

Volume % mixture

Sample Number	H ₂ O ₂	NH ₄ OH	DIW
1	100	0	0
2	0	100	0
3	0	0	100
4	50	50	0
5	50	0	50
6	0	50	50
7	66.67	16.67	16.67
8	16.67	66.67	16.67
9	16.67	16.67	66.67
10	33.3	33.3	33.3

Fitting model,

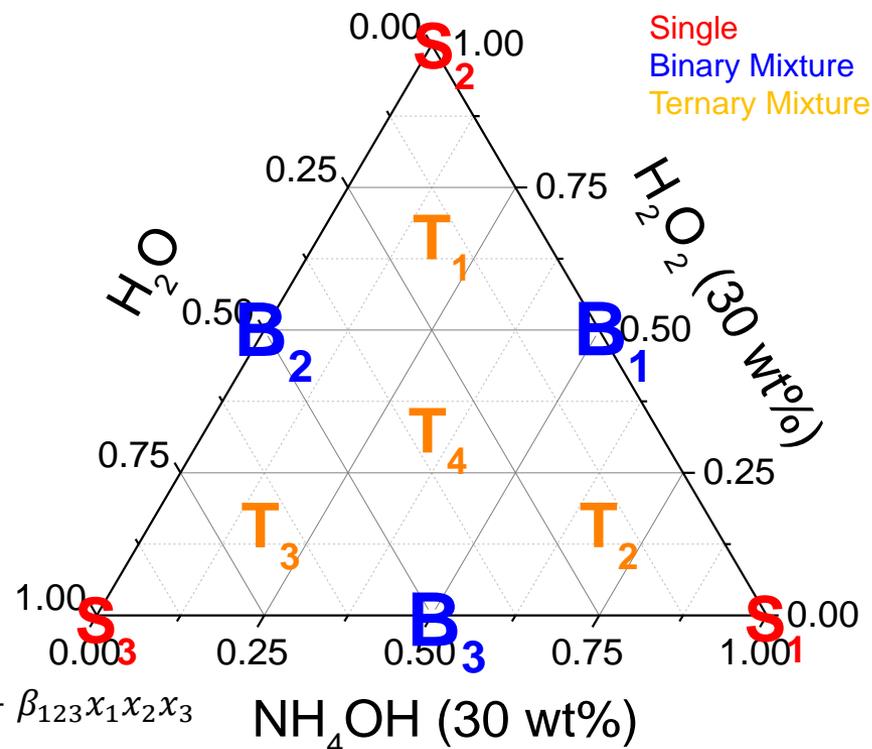
$$Y = \sum_{i=1}^3 \beta_i x_i + \sum \sum_{i < j}^3 \beta_{ij} x_i x_j + \sum \sum_{i < j}^3 \delta_{ij} \beta_{ij} x_i x_j (x_i - x_j) + \beta_{123} x_1 x_2 x_3$$

x_1 (30 wt% H₂O₂), x_2 (30 wt% NH₄OH) and x_3 (H₂O)

Logit transformation $Y = \ln(y/(1 - y))$

where y is the cleaning efficiency expressed in the range of 0 to 1.

Augmented simplex-centroid design used to optimize composition of H₂O₂-NH₄OH mixtures



H₂O₂-NH₄OH mixtures and Their Optimization

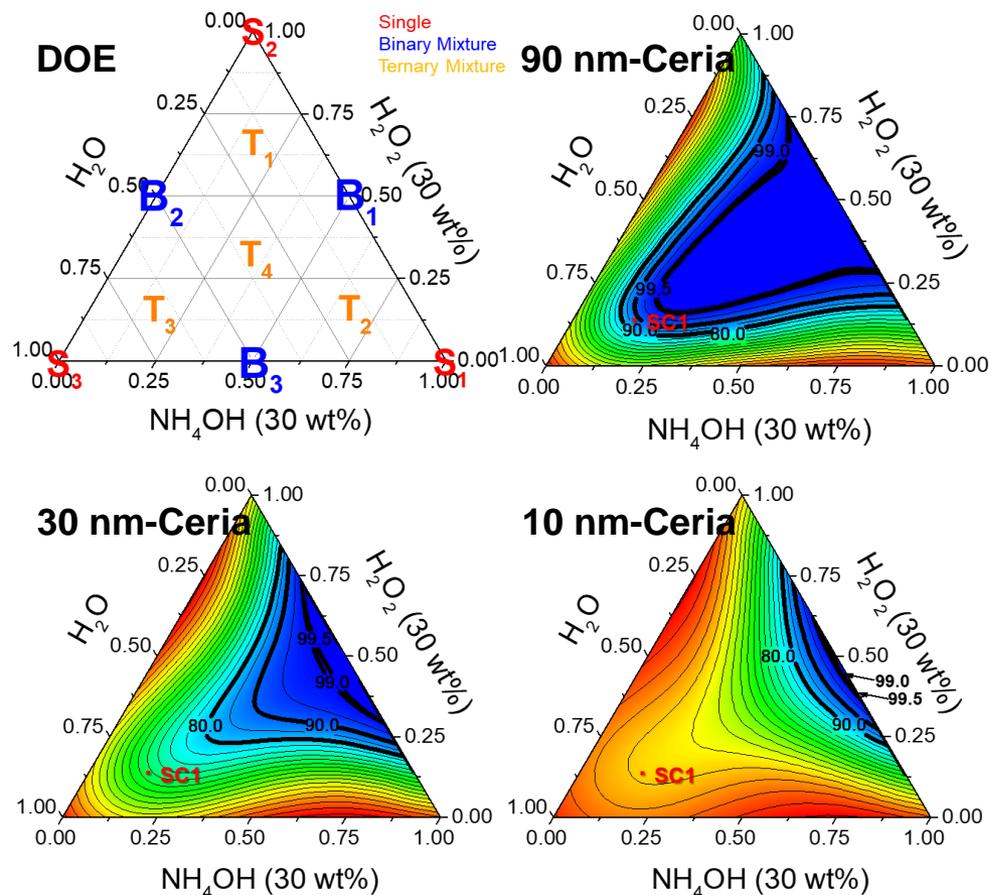
Summary of Optimization of H₂O₂-based Alkaline Solutions

Solution Number	H ₂ O ₂ (30 wt%)	NH ₄ OH (30 wt%)	DIW	pH	Rq (nm)	Cleaning Efficiency		
						10 nm	30 nm	90 nm
1	100	0	0	4.5	0.6	<5 %	<5 %	<5 %
2	0	100	0	13.7	0.9	19 %	23 %	60 %
3	0	0	100	6.0	0.6	<5.0 %	<5.0 %	<5 %
4	50	50	0	13.2	0.8	98 %	99 %	99 %
5	50	0	50	4.7	0.6	<5 %	<5 %	<5 %
6	0	50	50	13.5	0.8	<5 %	<5 %	<5 %
7	66.66	16.67	16.67	12.5	0.7	28 %	56 %	89 %
8	16.67	66.66	16.67	13.4	0.7	27 %	62 %	89 %
9	16.67	16.67	66.66	12.8	0.7	31 %	68 %	90 %
10	33.3	33.3	33.3	12.9	0.8	43 %	89 %	99 %
SC1	14.3	14.3	71.4	12.0	0.7	19 %	58 %	94 %

Table. Surface roughness (Rq) and cleaning efficiencies of the ten compositions tested based on full cubic model, and SC1 solution.

H₂O₂-NH₄OH mixtures and Their Optimization

Summary of Optimization of H₂O₂-NH₄OH mixtures



Cleaning efficiencies of SC1 solution

	Experimental	Predicted
10 nm	19 %	23 %
30 nm	58 %	61 %
90 nm	94 %	90 %

$$Y_{90nm} = -2.9x_1 + 0.4x_2 - 2.9x_3 + 24.5x_1x_2 - 0.04x_1x_3 - 6.7x_2x_3 + 145.1x_1x_2(x_1 - x_2) + 7.8x_1x_3(x_1 - x_3) - 21.8x_2x_3(x_2 - x_3) - 26.2x_1x_2x_3$$

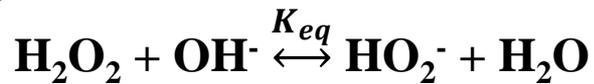
$$Y_{30nm} = -2.9x_1 - 1.2x_2 - 2.9x_3 + 30.3x_1x_2 - 0.04x_1x_3 - 0.03x_2x_3 - 3.5x_1x_2(x_1 - x_2) - 37.7x_1x_3(x_1 - x_3) - 19.8x_2x_3(x_2 - x_3) - 20.8x_1x_2x_3$$

$$Y_{10nm} = -3.0x_1 - 1.5x_2 - 3.0x_3 + 25.1x_1x_2 - 0.1x_1x_3 - 3.0x_2x_3 - 12.5x_1x_2(x_1 - x_2) - 3.9x_1x_3(x_1 - x_3) - 11.8x_2x_3(x_2 - x_3) - 13.7x_1x_2x_3$$

A contour plot of cleaning efficiencies showing the synergistic effect of H₂O₂ (30 wt%), NH₄OH (30 wt%), and H₂O mixtures; 90 nm-ceria, 30 nm-ceria, and 10 nm-ceria..

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Perhydroxyl ion concentration



$$pK_a = 11.6$$

$$\text{where } K_{eq} = \frac{[\text{HO}_2^-]}{[\text{OH}^-][\text{H}_2\text{O}_2]} = \frac{K_{ion}}{K_W}$$

$$K_{ion} = \frac{[\text{H}^+][\text{HO}_2^-]}{[\text{H}_2\text{O}_2]} \quad (2.24 \times 10^{-12} \text{ mol/L at } 25 \text{ }^\circ\text{C}) \text{ for } \text{H}_2\text{O}_2$$

$$K_W \text{ for water is } 1.0 \times 10^{-14} \text{ mol}^2/\text{L}^2 \text{ at } 25 \text{ }^\circ\text{C}$$

X = starting molar concentration of NH_4OH

Y = starting molar concentration of H_2O_2

Z = formed molar concentration of $[\text{HO}_2^-]$ at equilibrium

$[\text{OH}^-]$ and $[\text{H}_2\text{O}_2]$ are the concentrations of hydroxyl ion and undecomposed hydrogen peroxide at equilibrium, respectively, which gives $[\text{OH}^-] = X - Z$ and $[\text{H}_2\text{O}_2] = Y - Z$

$$K_{eq} = \frac{[\text{HO}_2^-]}{[\text{OH}^-][\text{H}_2\text{O}_2]} = \frac{Z}{(X - Z)(Y - Z)}$$

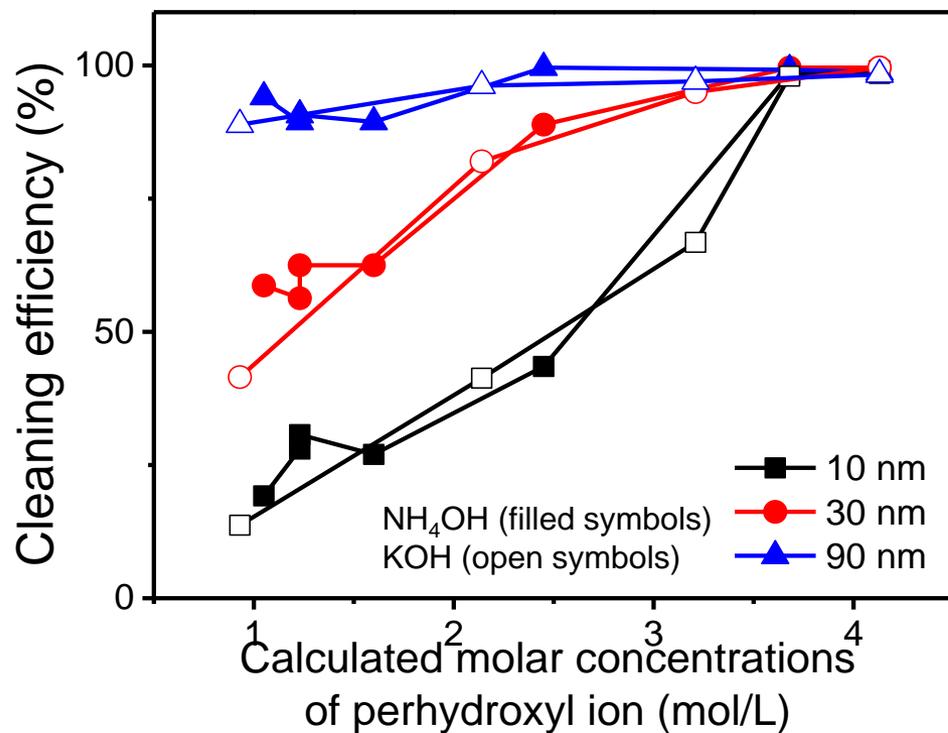
$$[\text{HO}_2^-] = \frac{R - \sqrt{R^2 - 4XY}}{2} \quad \text{where } R = X + Y + 1/K_{eq}$$

$[\text{HO}_2^-]$ has a maximum when $R^2 = 4XY$

Maximum value of $[\text{HO}_2^-] = X = Y$

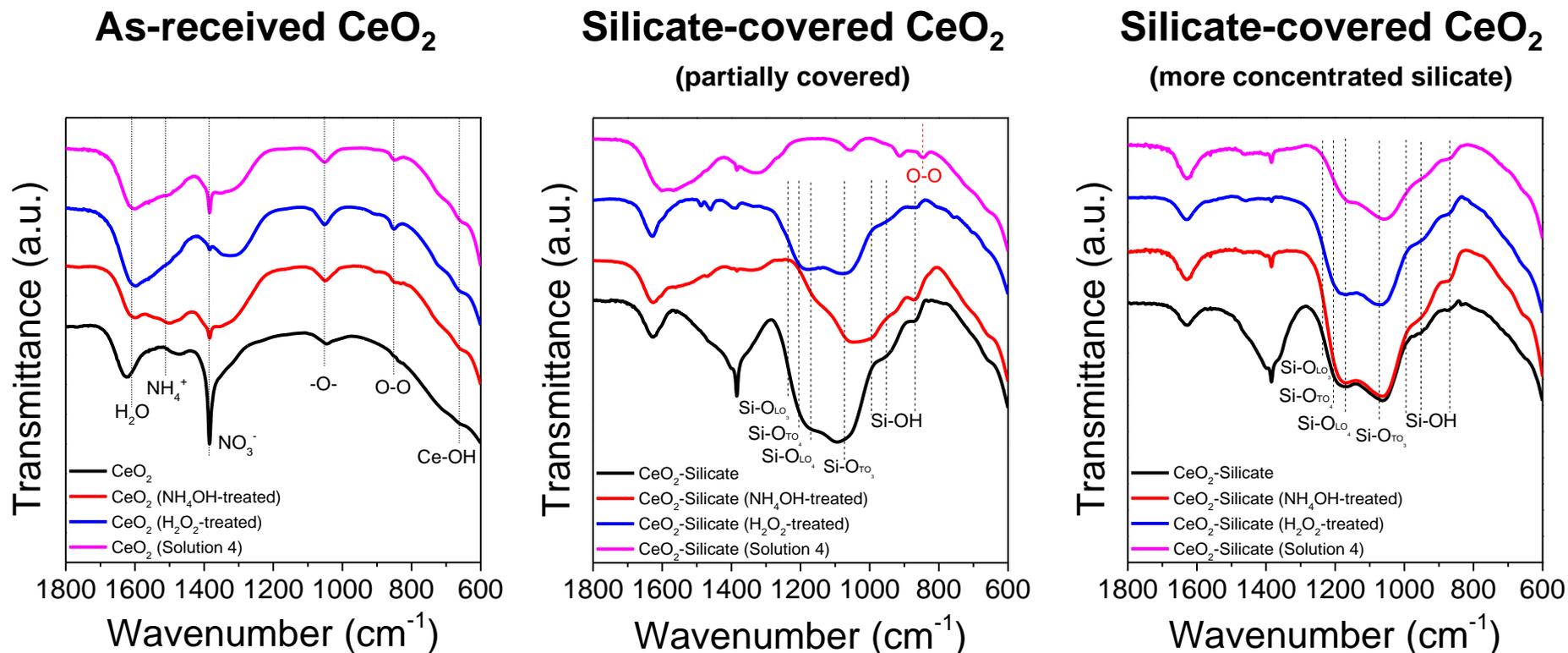
Calculated molar concentration of perhydroxyl anion of cleaning solutions and their cleaning efficiencies

Cleaning efficiency as a function of perhydroxyl ions in mixtures of H₂O₂-based alkaline cleaning solution



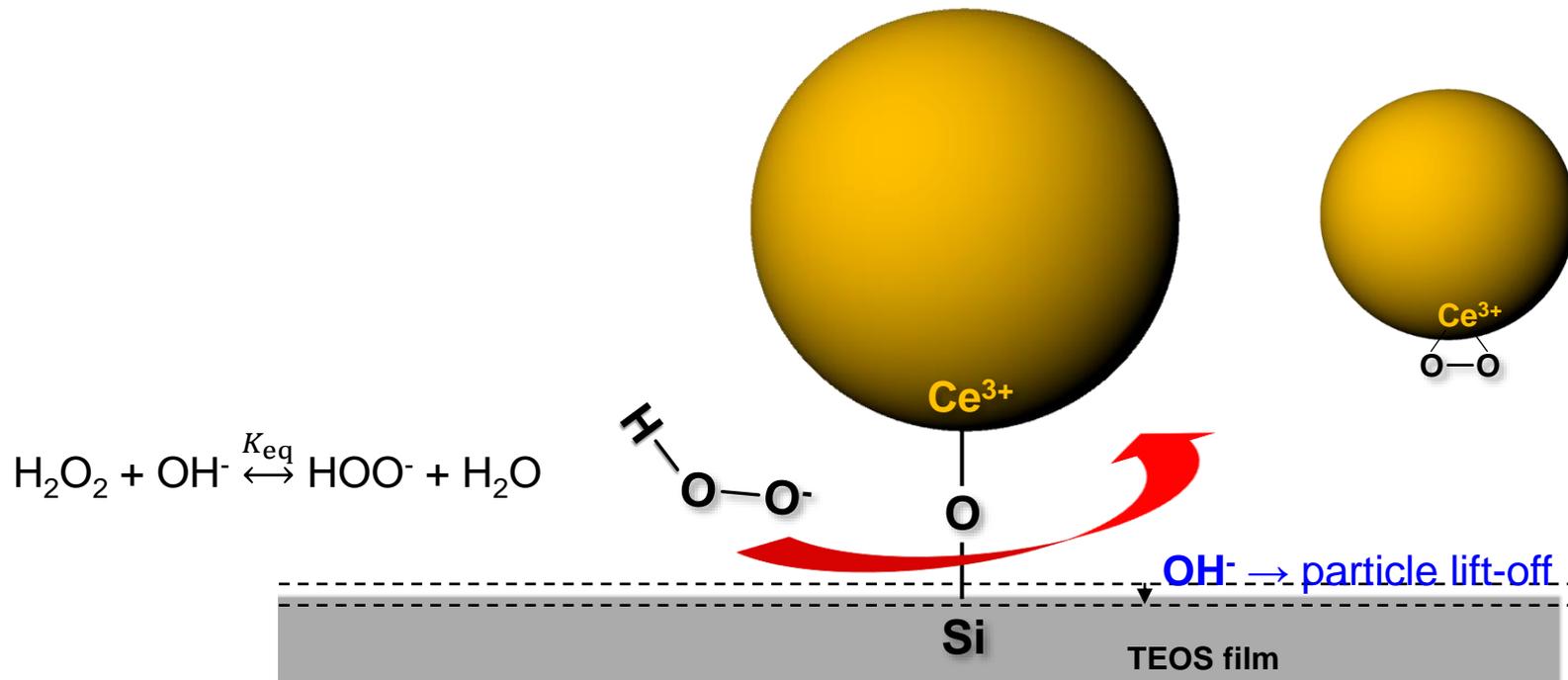
Solution Number	Perhydroxyl ions (mol/L)	Cleaning Efficiency		
		10 nm	30 nm	90 nm
1	0.00	<5 %	<5 %	<5 %
2	0.00	19 %	23 %	60 %
3	0.00	<5.0 %	<5.0 %	<5 %
4	3.68	98 %	99 %	99 %
5	0.00	<5 %	<5 %	<5 %
6	0.00	<5 %	<5 %	<5 %
7	1.23	28 %	56 %	89 %
8	1.60	27 %	62 %	89 %
9	1.23	31 %	68 %	90 %
10	2.45	43 %	89 %	99 %
SC1	1.05	19 %	58 %	94 %
NH ₄ OH-1	4.13	99 %	99 %	99 %
KOH-1	3.26	67 %	95 %	97 %
KOH-2	2.17	41 %	82 %	96 %
KOH-3	0.93	14 %	41 %	89 %
KOH-4	4.13	98 %	99 %	98 %

Cleaning mechanism in H_2O_2 -based alkaline solutions and breakage of Ce-O-Si bonds



FT-IR spectra of ceria particles in the region of $1800\text{-}600\text{ cm}^{-1}$. As-received, silicate (0.01 wt%) silicate (0.1 wt%) covered 10 nm-ceria particles that were reacted with four different solutions (H_2O , H_2O_2 (30 wt%), NH_4OH (30 wt%), and H_2O_2 - NH_4OH mixture (50/50 volume ratios)).

Schematic illustration of the removal of ceria particles by H₂O₂-based alkaline cleaning solution



Bond type		Bond dissociation energy (kJ/mol)
Perhydroxyl anion (OOH)	O-O	210
	O-H	336
Hydroxyl ion	O-H	487
	Ce-O-Si	790
	Si-O	452

Table. Known binding energy data

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Smaller ceria particles are more difficult to remove from oxide surfaces after CMP.

We showed that high pH H_2O_2 -based cleaning solutions, aided by ultrasonic energy, can almost completely remove ceria particles down to 10 nm in size as determined by AFM imaging and counting.

Highest removal efficiencies were obtained when the molar concentration of the perhydroxyl ions $[\text{HO}_2^-]$ is the highest possible in the cleaning solution.

Acknowledgement

1. **Dr. S.V. Babu**
2. **Ebara Corporation**
3. **Solvay**

